

Q3 75. (Amended) A method for manufacturing semiconductors by using the inspection apparatus of claim 71 or 72.

Q4 81. (Amended) A device manufacturing method for evaluating a wafer during manufacturing process by using the inspection apparatus of any one of claims 77 to 79.

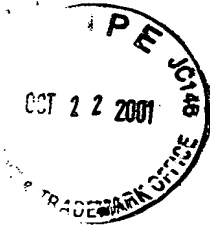
Please add new claims 101-104 as follows:

101. (New) A method for manufacturing semiconductor devices wherein a wafer during a manufacturing process or after processing is evaluated by using the inspection apparatus of claim 53.

Q5 102. (New) A method for manufacturing semiconductors by using the inspection apparatus of claim 73.

103. (New) A method for manufacturing semiconductors by using the inspection apparatus of claim 74.

104. (New) A device manufacturing method for evaluating a wafer during manufacturing process by using the inspection apparatus of claim 80.



VERSION WITH MARKINGS TO SHOW CHANGES MADE
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IN THE CLAIMS:

Claims 53, 55, 75 and 81 have been amended as follows:

53. (Amended) The inspection apparatus of claim ~~52~~ 51 or 52 wherein the apparatus is constructed so that an energizing condition of an objective lens is obtained under a state where a pattern on a wafer is electrically charged.

55. (Amended) A method for manufacturing semiconductor devices wherein a wafer during a manufacturing process or after processing is evaluated by using the inspection apparatus of any one of claims ~~51-54~~ 51, 52 or 54.

75. (Amended) A method for manufacturing semiconductors by using the inspection apparatus of ~~any one of claims 71 to 74~~ claim 71 or 72.

81. (Amended) A device manufacturing method for evaluating a wafer during manufacturing process by using the inspection apparatus of any one of claims 77 to ~~80~~ 79.

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